
October 22 (Thu.), 2026

[Oral 11] CMP Consumables (II)

11:25-12:45

International Conference Hall (B1F)

● Session Chair: Andy Tuan (Linx Consulting Inc., Taiwan)

11:25-11:45

[Oral 11-1]

[The Interconnect Advantage: CMP Powering AI and HBM](#)

Ping Tzeng, Jingzhi Chen (Merck, Taiwan), and Hongjun Zhou (The Electronics Business of Merck KGaA, Germany)

11:45-12:05

[Oral 11-2]

[Study on the Mechanism of unCMP Caused by Plastic Deformation of the Head Membrane in CMP Equipment and Its Improvement](#)

KyongKyu Myong, Jubong Lee, Younggeun Lee, Yoo-Yong Lee, Ki Ho Bae, and Hoyoung Kim (Samsung Electronics Co., Ltd., Korea)

12:05-12:25

★[Oral 11-3]

[Identifying the Origin of Small Particle Defects in Oxide Chemical Mechanical Planarization](#)

Seungmoon Choi, Hyeonjeong Lee, Hyunho Kim, Junil Cho, and Taesung Kim (Sungkyunkwan Univ., Korea)

12:25-12:45

[Oral 11-4]

[New Particle and Chemistry Technology for Metals IC CMP Slurries](#)

Yu Yu Chou, Howl Hsu (Entegris Co., Ltd., Taiwan), Brian Reiss, and Na Zhang (Entegris Inc., USA)